

**CCD 4 Channel Vertical Driver**

**Features**

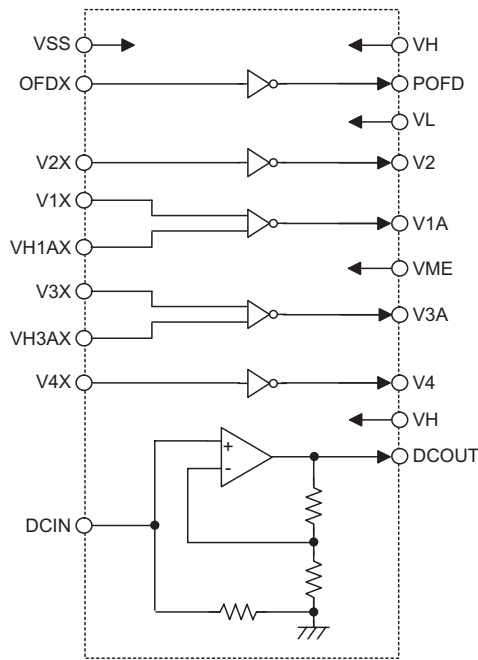
- Input voltage: 3.0V~5.5V
- Built-in seven circuits
  - 2-level output:
    - 2 circuits for vertical CCD clock driver  
output voltage level (typ.) = -9V to 0V
    - 3-level output:
      - 2 circuits for vertical CCD clock driver  
output voltage level (typ.) = -9V to 15V
  - 2-level output:
    - 1 circuit for shutter driver  
output voltage level (typ.) = -9V to 15V
- Switchable between NTSC (EIA) and PAL (CCIR) modes
- 16-pin SSOP, 16/20-pin TSSOP package

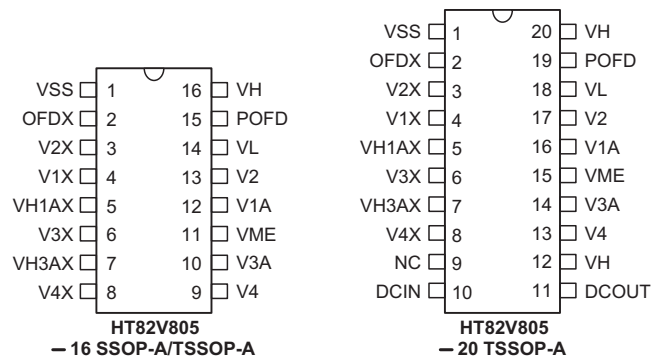
**General Description**

HT82V805 is a CMOS vertical clock driver and shutter driver IC for CCD area sensors. It has the capability of

converting the voltage and impedance from the CMOS level.

**Block Diagram**



**Pin Assignment**

**Pin Description**

Pin Name	I/O	Description
VSS	—	Negative power supply, ground
OFDX	I	Electronic shutter pulse input
V1X, V2X, V3X, V4X	I	Vertical transfer pulse input
VH1AX, VH3AX	I	Pulse that transfers the charge of the photo-diode to the vertical shift register.
NC	—	No connection
DCIN	I	OP-Amp input (internal pull-down resistor)
DCOUT	O	OP-Amp output
VH	—	Power supply for high level of V1A, V3A
V4	O	Pulse to drive vertical CCD shift register (2 level: VME, VL)
V3A	O	Pulse to drive vertical CCD shift register (3 level: VME, VL, VH)
VME	—	Power supply for intermediate level of V1A, V3A
V1A	O	Pulse to drive vertical CCD shift register (3 level: VME, VL, VH)
V2	O	Pulse to drive vertical CCD shift register (2 level: VME, VL)
VL	—	Power supply for all low level output pulses
POFD	O	Electronic shutter pulse output (2 level: VL, VH)

**Absolute Maximum Ratings**

Supply Voltage ..... $V_{SS}-0.3V$  to  $V_L+35V$       Storage Temperature ..... $-55^{\circ}C$  to  $150^{\circ}C$   
 Input Voltage ..... $V_{SS}-0.3V$  to  $V_H+0.3V$       Operating Temperature ..... $-25^{\circ}C$  to  $70^{\circ}C$

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

**Recommended Operating Conditions**

Symbol	Parameter	Value	Unit
$V_H$	Supply Voltage	$-0.3 \sim V_L+35$	V
$V_L$		$0 \sim -10$	V
VME		$V_L-0.3 \sim 3.0$	V
V1A, V2, V3A, V4, POFD	Output Voltage	$V_L-0.3 \sim V_H+0.3$	V

**Logic Function Table**

Input				Output		
V1X, V3X	VH1AX, VH3AX	V2X, V4X	OFDX	V1A, V3A	V2, V4	POFD
L	L	—	—	VH	—	—
H	L	—	—	Z	—	—
L	H	—	—	VME	—	—
H	H	—	—	VL	—	—
—	—	L	—	—	VME	—
—	—	H	—	—	VL	—
—	—	—	L	—	—	VH
—	—	—	H	—	—	VL

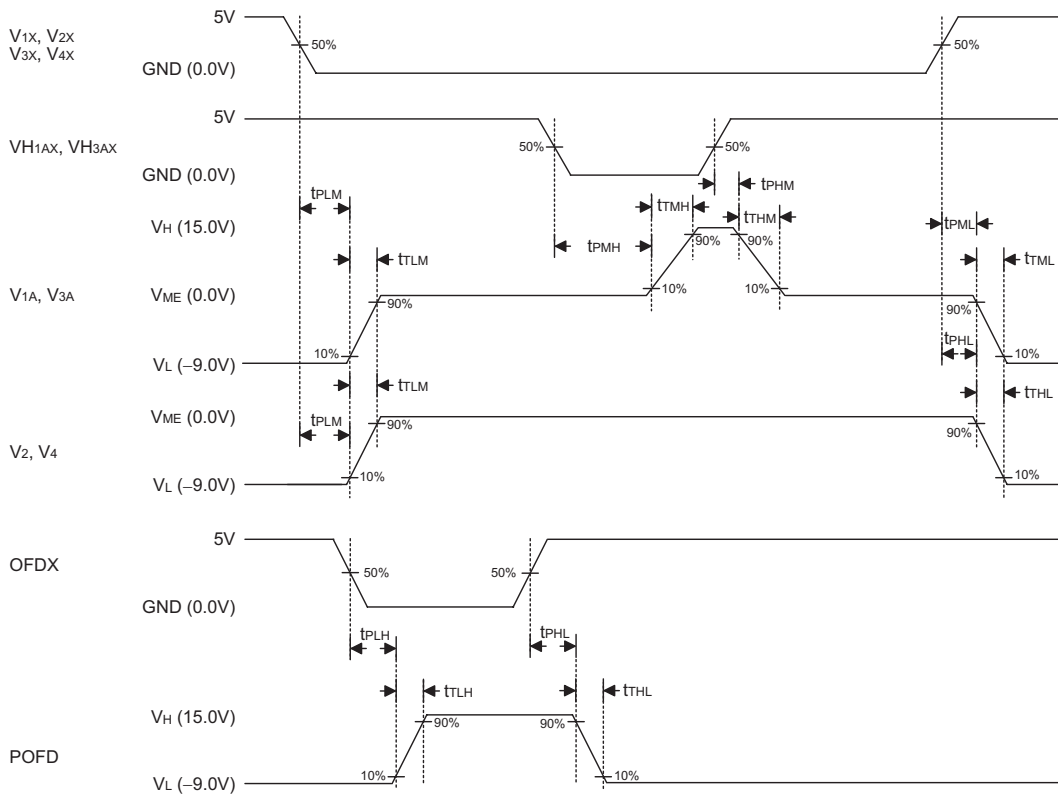
**D.C. Characteristics**
 $V_H=15V, V_L=-9V, V_{ME}=0V, T_a=25^\circ C$ 

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{DD}$	Logic Supply Voltage	—	3.0	3.3	5.5	V
$V_H$	Supply Voltage	—	14.5	15	15.5	V
$V_L$	Supply Voltage	—	-9.5	-8.5	-7.5	V
$V_{IH}$	High Level Input Voltage	—	2.4	—	—	V
$V_{IL}$	Low Level Input Voltage	—	—	—	1.2	V
$I_{VH}$	Operating Current	Shutter speed=100kHz	—	3.8	—	mA
$I_{VL}$			—	-2	—	mA
$I_{VME}$			—	-6.5	—	mA
$I_{OL}$	Output Current	$V_{1A}, V_2, V_{3A}, V_4=-9.0V$	—	37	—	mA
$I_{OM1}$		$V_{1A}, V_2, V_{3A}, V_4=-0.5V$	—	-15	—	mA
$I_{OM2}$		$V_{1A}, V_{3A}=0.5V$	—	13.5	—	mA
$I_{OH}$		$V_{1A}, V_{3A}=14.5V$	—	-18	—	mA
$I_{OSL}$		$O_{FDX}=-8.0V$	—	18	—	mA
$I_{OSH}$		$O_{FDX}=14.5V$	—	-10.5	—	mA
G		OP-Amp Gain	$DC_{IN}=1\sim 3V$	3.4	3.9	4.2

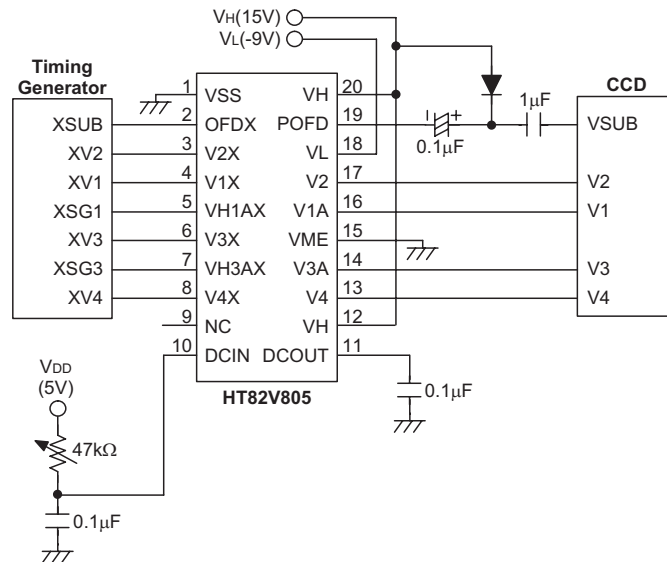
**A.C. Characteristics**
 $T_a=25^\circ C$ 

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{PLM}$	Delay Time	$V_H=15V, V_L=-8.5V, V_{ME}=0V$	—	55	80	ns
$t_{PMH}$		$V_H=15V, V_L=-8.5V, V_{ME}=0V$	—	50	90	ns
$t_{PLH}$		$V_H=15V, V_L=-8.5V, V_{ME}=0V$	—	55	100	ns
$t_{PML}$		$V_H=15V, V_L=-8.5V, V_{ME}=0V$	—	45	130	ns
$t_{PHM}$		$V_H=15V, V_L=-8.5V, V_{ME}=0V$	—	50	120	ns
$t_{PHL}$		$V_H=15V, V_L=-8.5V, V_{ME}=0V$	—	55	100	ns
$t_{TLM}$	Rising Time	$V_H=15V, V_L=-8.5V, V_{ME}=0V$	—	370	900	ns
$t_{TMH}$		$V_H=15V, V_L=-8.5V, V_{ME}=0V$	—	785	900	ns
$t_{TLH}$		$V_H=15V, V_L=-8.5V, V_{ME}=0V$	—	70	140	ns
$t_{TML}$		$V_H=15V, V_L=-8.5V, V_{ME}=0V$	—	300	700	ns
$t_{THM}$		$V_H=15V, V_L=-8.5V, V_{ME}=0V$	—	630	960	ns
$t_{THL}$		$V_H=15V, V_L=-8.5V, V_{ME}=0V$	—	45	120	ns

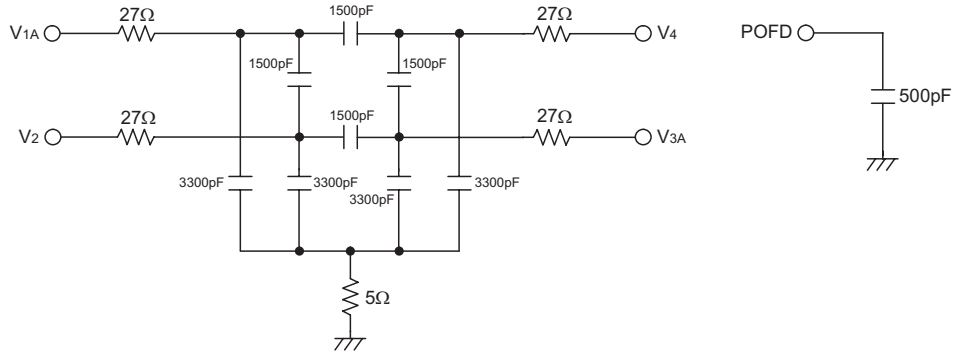
**Timing Diagrams**



**Application Circuits**

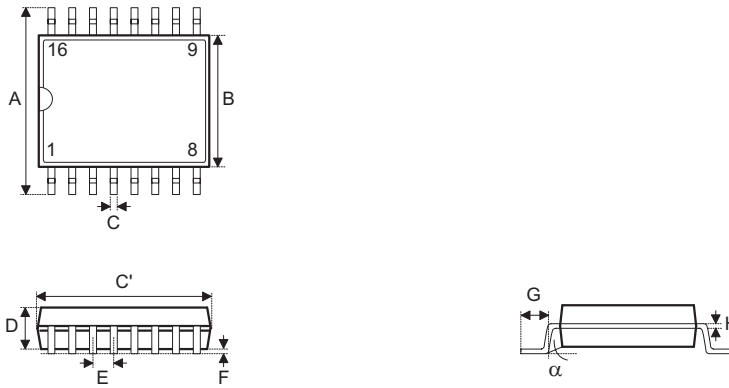


Equivalent Circuits



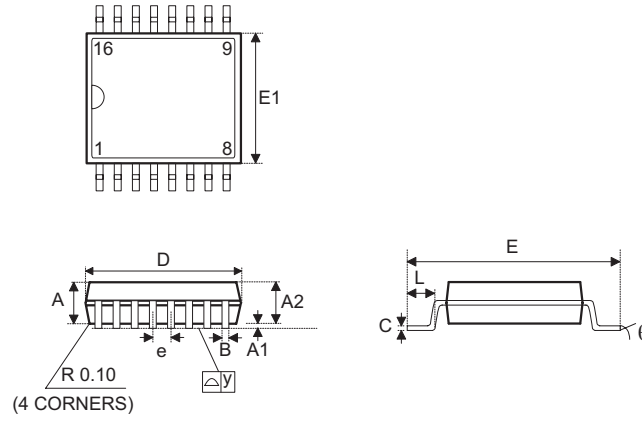
**Package Information**

**16-pin SSOP (150mil) Outline Dimensions**



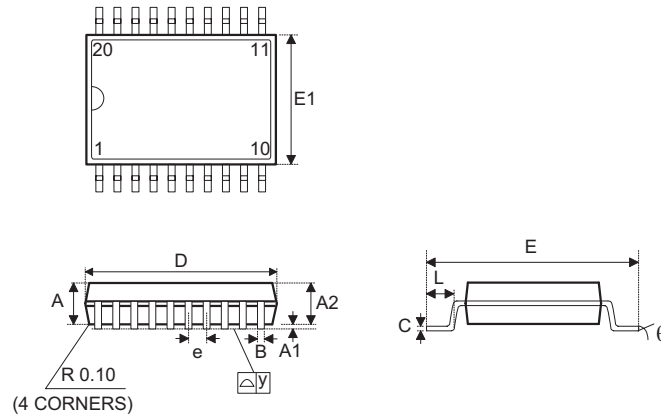
Symbol	Dimensions in mil		
	Min.	Nom.	Max.
A	228	—	244
B	150	—	157
C	8	—	12
C'	189	—	197
D	54	—	60
E	—	25	—
F	4	—	10
G	22	—	28
H	7	—	10
α	0°	—	8°

**16-pin TSSOP Outline Dimensions**



Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	1	—	1.05
A1	0.05	—	0.15
A2	1.05	—	1.2
B	—	0.25	—
C	0.11	—	0.15
D	4.9	—	5.1
E	6.2	—	6.6
E1	4.3	—	4.5
e	—	0.65	—
L	0.5	—	0.7
y	—	—	0.076
$\theta$	0°	—	8°

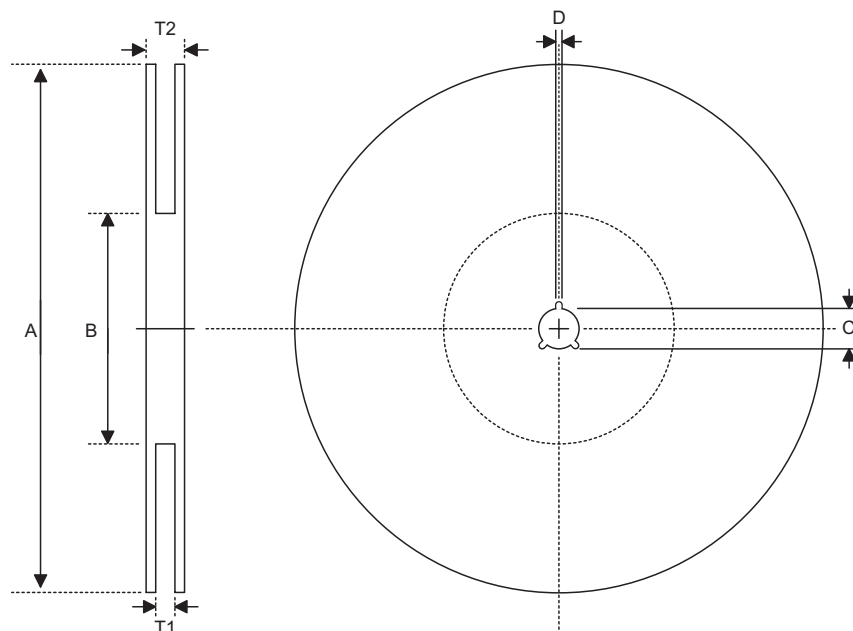


**20-pin TSSOP Outline Dimensions**


Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	1.05	—	1.2
A1	0.05	—	0.15
A2	0.95	—	1.05
B	—	0.22	—
C	0.13	—	0.17
D	6.4	—	6.6
E	6.3	—	6.5
E1	4.3	—	4.5
e	—	0.65	—
L	0.45	—	0.75
y	—	—	0.1
θ	0°	—	8°

**Product Tape and Reel Specifications**

**Reel Dimensions**



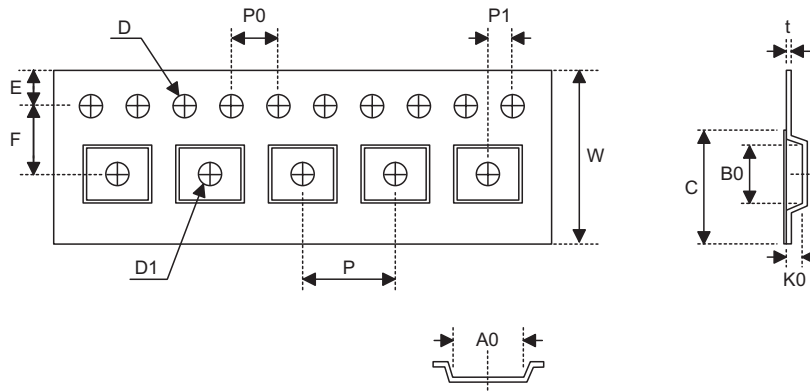
**SSOP 16S**

Symbol	Description	Dimensions in mm
A	Reel Outer Diameter	330±1.0
B	Reel Inner Diameter	62±1.5
C	Spindle Hole Diameter	13.0+0.5 -0.2
D	Key Slit Width	2.0±0.5
T1	Space Between Flange	12.8+0.3 -0.2
T2	Reel Thickness	18.2±0.2

**TSSOP 16L**

Symbol	Description	Dimensions in mm
A	Reel Outer Diameter	330±1
B	Reel Inner Diameter	62±1.5
C	Spindle Hole Diameter	13+0.5 -0.2
D	Key Slit Width	2±0.5
T1	Space Between Flange	16.8+0.3 -0.2
T2	Reel Thickness	22.2±0.2

Carrier Tape Dimensions



SSOP 16S

Symbol	Description	Dimensions in mm
W	Carrier Tape Width	12.0+0.3 -0.1
P	Cavity Pitch	8.0±0.1
E	Perforation Position	1.75±0.1
F	Cavity to Perforation (Width Direction)	5.5±0.1
D	Perforation Diameter	1.55±0.1
D1	Cavity Hole Diameter	1.5+0.25
P0	Perforation Pitch	4.0±0.1
P1	Cavity to Perforation (Length Direction)	2.0±0.1
A0	Cavity Length	6.4±0.1
B0	Cavity Width	5.2±0.1
K0	Cavity Depth	2.1±0.1
t	Carrier Tape Thickness	0.30±0.05
C	Cover Tape Width	9.3

TSSOP 16L

Symbol	Description	Dimensions in mm
W	Carrier Tape Width	16+0.3 -0.1
P	Cavity Pitch	8±0.1
E	Perforation Position	1.75±0.1
F	Cavity to Perforation (Width Direction)	7.5±0.5
D	Perforation Diameter	1.5+0.1
D1	Cavity Hole Diameter	1.5+0.1
P0	Perforation Pitch	4±0.1
P1	Cavity to Perforation (Length Direction)	2±0.1
A0	Cavity Length	6.8±0.1
B0	Cavity Width	5.4±0.1
K0	Cavity Depth	1.6±0.1
t	Carrier Tape Thickness	0.3±0.013
C	Cover Tape Width	13.3

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